

December 2000

QFET™

## **FQD7N10 / FQU7N10**

#### 100V N-Channel MOSFET

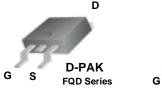
#### **General Description**

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

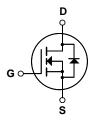
This advanced technology is especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation modes. These devices are well suited for low voltage applications such as audio amplifiers, high efficiency switching DC/DC converters, and DC motor control.

#### **Features**

- 5.8A, 100V,  $R_{DS(on)} = 0.35\Omega @V_{GS} = 10 \text{ V}$
- Low gate charge (typical 5.8 nC)
- Low Crss (typical 10 pF)
- Fast switching
- 100% avalanche tested
- · Improved dv/dt capability







### Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter		FQD7N10 / FQU7N10	Units	
V <sub>DSS</sub>	Drain-Source Voltage		100	V	
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> = 25°	C)	5.8	А	
	- Continuous (T <sub>C</sub> = 100	°C)	3.67	А	
I <sub>DM</sub>	Drain Current - Pulsed	(Note 1)	23.2	Α	
V <sub>GSS</sub>	Gate-Source Voltage		± 25	V	
E <sub>AS</sub>	Single Pulsed Avalanche Energy	(Note 2)	50	mJ	
I <sub>AR</sub>	Avalanche Current	(Note 1)	5.8	Α	
E <sub>AR</sub>	Repetitive Avalanche Energy	(Note 1)	2.5	mJ	
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	6.0	V/ns	
$P_{D}$	Power Dissipation (T <sub>A</sub> = 25°C) *		2.5	W	
	Power Dissipation (T <sub>C</sub> = 25°C)		25	W	
	- Derate above 25°C		0.2	W/°C	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150	°C	
T <sub>L</sub>	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C	

#### **Thermal Characteristics**

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		5.0	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient *		50	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		110	°C/W

<sup>\*</sup> When mounted on the minimum pad size recommended (PCB Mount)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Cha	aracteristics					
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V, I}_{D} = 250 \mu\text{A}$	100			V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	$I_D$ = 250 $\mu$ A, Referenced to 25°C		0.1		V/°C
I <sub>DSS</sub>	Zero Cata Valla va Brain Commant	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V			1	μΑ
	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 80 V, T <sub>C</sub> = 125°C			10	μΑ
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 25 V, V <sub>DS</sub> = 0 V			100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	V <sub>GS</sub> = -25 V, V <sub>DS</sub> = 0 V			-100	nA
On Cha	aracteristics					
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	2.0		4.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 2.9 A		0.28	0.35	Ω
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 40 V, I <sub>D</sub> = 2.9 A (Note 4)		3.3		S
C <sub>oss</sub> C <sub>rss</sub>	Output Capacitance  Reverse Transfer Capacitance	f = 1.0 MHz		60 10	75 13	pF pF
Orss	Reverse Transfer Capacitance			10	13	рг
Switch	ing Characteristics					
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 50 V, I <sub>D</sub> = 7.3 A,		7	25	ns
t <sub>r</sub>	Turn-On Rise Time	$R_G = 25 \Omega$		24	60	ns
t <sub>d(off)</sub>	Turn-Off Delay Time			13	35	ns
t <sub>f</sub>	Turn-Off Fall Time	(Note 4, 5)		19	50	ns
Qg	Total Gate Charge	$V_{DS} = 80 \text{ V}, I_{D} = 7.3 \text{ A},$		5.8	7.5	nC
$Q_{gs}$	Gate-Source Charge	V <sub>GS</sub> = 10 V		1.4		nC
$Q_{gd}$	Gate-Drain Charge	(Note 4, 5)		2.5		nC
	Source Diede Characteristics of	nd Maximum Ratings				
Drain-9	SOURCE LINOOE CHARACTERISTICS AT				1	
	Source Diode Characteristics and Maximum Continuous Drain-Source Dic				5.8	Α
Drain-S		ode Forward Current			5.8 23.2	A
I <sub>S</sub>	Maximum Continuous Drain-Source Dic	ode Forward Current				
I <sub>S</sub> I <sub>SM</sub>	Maximum Continuous Drain-Source Did Maximum Pulsed Drain-Source Diode F	ode Forward Current Forward Current			23.2	Α

- $\label{eq:Notes:Notes:1} \begin{tabular}{ll} \textbf{Notes:} \\ \textbf{1.} & \textbf{Repetitive Rating: Pulse width limited by maximum junction temperature} \\ \textbf{2.} & \textbf{L} = 2.23 \text{mH}, \textbf{I}_{AS} = 5.8 \text{A}, \textbf{V}_{DD} = 25 \text{V}, \textbf{R}_{G} = 25 \ \Omega, \textbf{Starting} \quad \textbf{T}_{J} = 25 ^{\circ} \textbf{C} \\ \textbf{3.} & \textbf{I}_{SD} \leq 7.3 \text{A}, & \textbf{id/dt} \leq 300 \text{A} \mu \text{s}, \textbf{V}_{DD} \leq \text{BV}_{DSS}, \textbf{Starting} \quad \textbf{T}_{J} = 25 ^{\circ} \textbf{C} \\ \textbf{4.} & \textbf{Pulse Test: Pulse width} \leq 300 \mu \text{s}, & \textbf{Duty cycle} \leq 2\% \\ \textbf{5.} & \textbf{Essentially independent of operating temperature} \\ \end{tabular}$

### **Typical Characteristics**

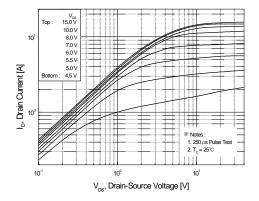


Figure 1. On-Region Characteristics

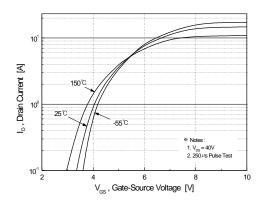


Figure 2. Transfer Characteristics

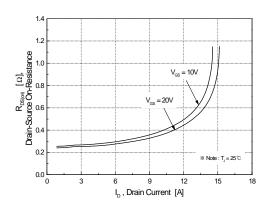


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

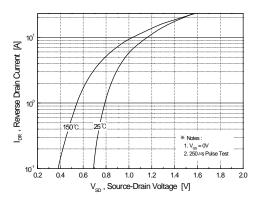


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

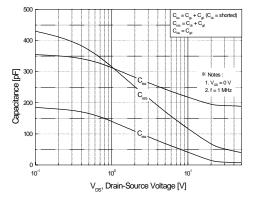


Figure 5. Capacitance Characteristics

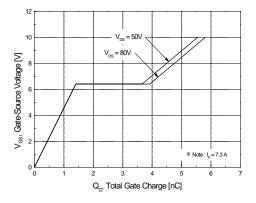
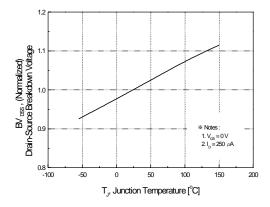


Figure 6. Gate Charge Characteristics

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### Typical Characteristics (Continued)



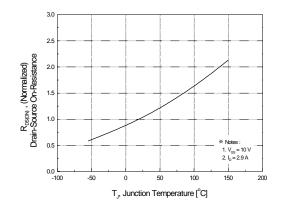
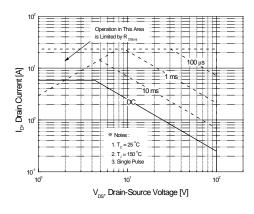


Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



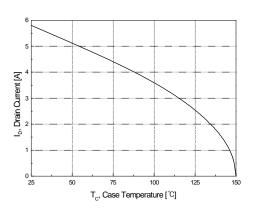


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

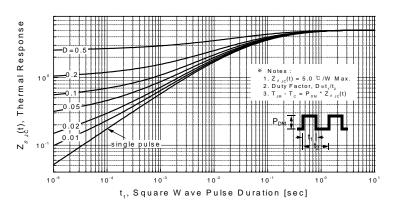
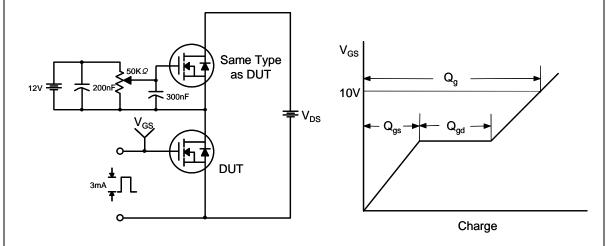


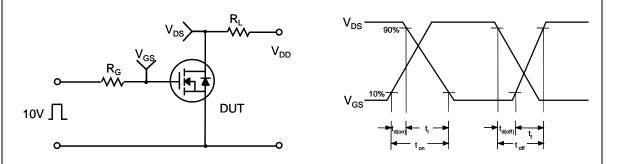
Figure 11. Transient Thermal Response Curve

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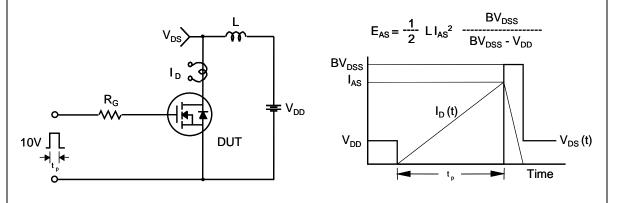
### **Gate Charge Test Circuit & Waveform**



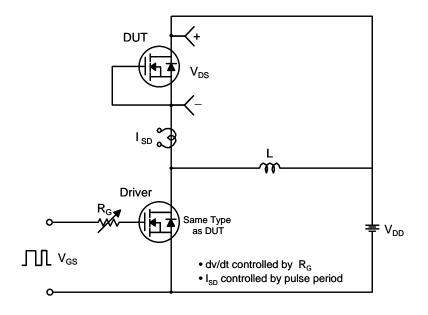
#### **Resistive Switching Test Circuit & Waveforms**

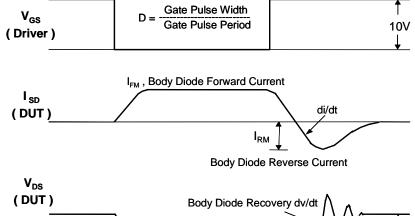


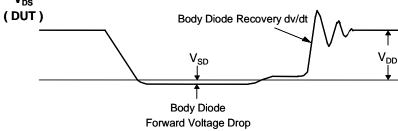
### **Unclamped Inductive Switching Test Circuit & Waveforms**



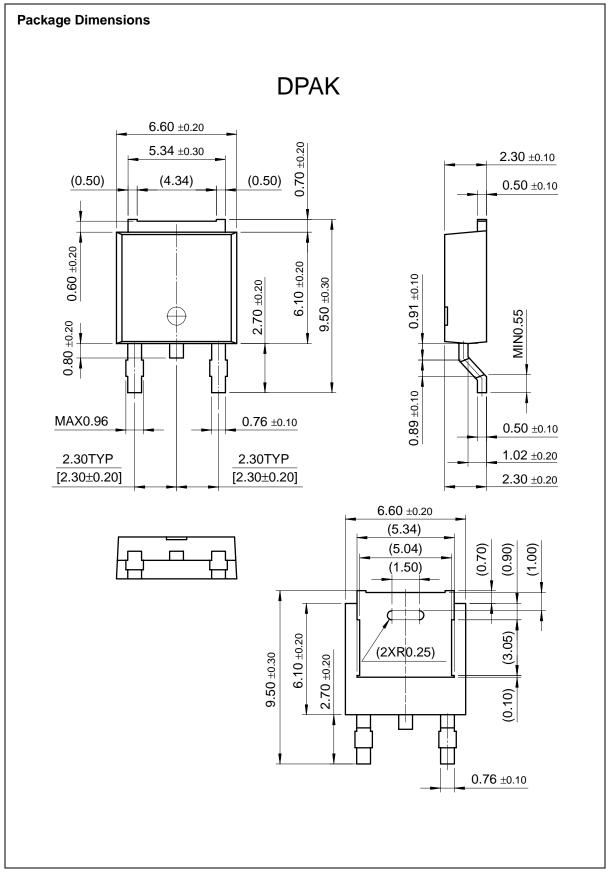
#### Peak Diode Recovery dv/dt Test Circuit & Waveforms

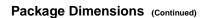




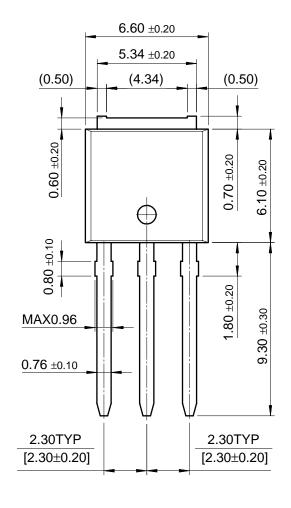


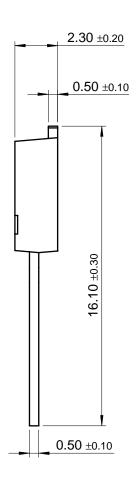
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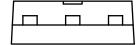




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## Product status/pricing/packaging

Product   Product status   Pricing*   Package type   Leads   Packing method
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FQD7N10TF	Full Production	\$0.34	TO-252(DPAK)	2	TAPE REEL
FQD7N10TM	Full Production	\$0.34	TO-252(DPAK)	2	TAPE REEL

<sup>\* 1,000</sup> piece Budgetary Pricing

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